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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f321ar9t6tr

PIN DESCRIPTION (Cont'd)

For external pin connection guidelines, refer to See "ELECTRICAL CHARACTERISTICS" on page 138.

Legend / Abbreviations for Table 2 **:**

Type: I = input, O = output, S = supply

Input level: A = Dedicated analog input

In/Output level: C = CMOS $0.3V_{DD}/0.7V_{DD}$
C_T= CMOS $0.3V_{DD}/0.7V_{DD}$ with input trigger
T_T= TTL 0.8V / 2V with Schmitt trigger

Output level: HS = 20mA high sink (on N-buffer only)

Port and control configuration:

– Input: float = floating, wpu = weak pull-up, int = interrupt [1], ana = analog

– Output: OD = open drain [2], PP = push-pull

Refer to "I/O PORTS" on page 46 for more details on the software configuration of the I/O ports.

The RESET configuration of each pin is shown in bold. This configuration is valid as long as the device is in reset state.

Table 2. Device Pin Description

Pin n°			Pin Name	Type	Level		Port						Main function (after reset)	Alternate function
							Input				Output			
LQFP64	LQFP44	LQFP32			Input	Output	float	wpu	int	ana	OD	PP		
1	-	-	PE4 (HS)	I/O	C_T	HS	**X**	X			X	X	Port E4	
2	-	-	PE5 (HS)	I/O	C_T	HS	**X**	X			X	X	Port E5	
3	-	-	PE6 (HS)	I/O	C_T	HS	**X**	X			X	X	Port E6	
4	-	-	PE7 (HS)	I/O	C_T	HS	**X**	X			X	X	Port E7	
5	2	28	PB0/PWM3	I/O	C_T		**X**	ei2			X	X	Port B0	PWM Output 3
6	3	-	PB1/PWM2	I/O	C_T		**X**	ei2			X	X	Port B1	PWM Output 2
7	4	-	PB2/PWM1	I/O	C_T		**X**	ei2			X	X	Port B2	PWM Output 1
8	5	29	PB3/PWM0	I/O	C_T		**X**		ei2		X	X	Port B3	PWM Output 0
9	6	30	PB4 (HS)/ARTCLK	I/O	C_T	HS	**X**	ei3			X	X	Port B4	PWM-ART External Clock
10	-	-	PB5 / ARTIC1	I/O	C_T		**X**	ei3			X	X	Port B5	PWM-ART Input Capture 1
11	-	-	PB6 / ARTIC2	I/O	C_T		**X**	ei3			X	X	Port B6	PWM-ART Input Capture 2
12	-	-	PB7	I/O	C_T		**X**		ei3		X	X	Port B7	
13	7	31	PD0/AIN0	I/O	C_T		**X**	X		X	X	X	Port D0	ADC Analog Input 0
14	8	32	PD1/AIN1	I/O	C_T		**X**	X		X	X	X	Port D1	ADC Analog Input 1
15	9	-	PD2/AIN2	I/O	C_T		**X**	X		X	X	X	Port D2	ADC Analog Input 2
16	10	-	PD3/AIN3	I/O	C_T		**X**	X		X	X	X	Port D3	ADC Analog Input 3
17	11	-	PD4/AIN4	I/O	C_T		**X**	X		X	X	X	Port D4	ADC Analog Input 4
18	12	-	PD5/AIN5	I/O	C_T		**X**	X		X	X	X	Port D5	ADC Analog Input 5
19	-	-	PD6/AIN6	I/O	C_T		**X**	X		X	X	X	Port D6	ADC Analog Input 6
20	-	-	PD7/AIN7	I/O	C_T		**X**	X		X	X	X	Port D7	ADC Analog Input 7
21	13	1	V_{AREF}	I									Analog Reference Voltage for ADC	
22	14	2	V_{SSA}	S									Analog Ground Voltage	

Pin n°			Pin Name	Type	Level		Port						Main function (after reset)	Alternate function
							Input				Output			
LQFP64	LQFP44	LQFP32			Input	Output	float	wpu	int	ana	OD	PP		
45	-	-	PA2	I/O	C_T		**X**	ei0			X	X	Port A2	
46	31	16	PA3 (HS)	I/O	C_T	HS	**X**		ei0		X	X	Port A3	
47	32	-	V_{DD_1}	S									Digital Main Supply Voltage	
48	33	-	V_{SS_1}	S									Digital Ground Voltage	
49	34	17	PA4 (HS)	I/O	C_T	HS	**X**	X			X	X	Port A4	
50	35	-	PA5 (HS)	I/O	C_T	HS	**X**	X			X	X	Port A5	
51	36	18	PA6 (HS)/SDAI	I/O	C_T	HS	**X**				T		Port A6	I^2C Data [1]
52	37	19	PA7 (HS)/SCLI	I/O	C_T	HS	**X**				T		Port A7	I^2C Clock [1]
53	38	20	V_{PP}/ ICCSEL	I									Must be tied low. In flash programming mode, this pin acts as the programming voltage input V_{PP}. See Section 12.9.2 for more details. High voltage must not be applied to ROM devices	
54	39	21	$\overline{RESET}$	I/O	C_T								Top priority non maskable interrupt.	
55	-	-	EVD										External voltage detector	
56	-	-	TLI	I	C_T				X				Top level interrupt input pin	
57	40	22	V_{SS_2}	S									Digital Ground Voltage	
58	41	23	OSC2 [3]	I/O									Resonator oscillator inverter output	
59	42	24	OSC1 [3]	I									External clock input or Resonator oscillator inverter input	
60	43	25	V_{DD_2}	S									Digital Main Supply Voltage	
61	44	26	PE0/TDO	I/O	C_T		**X**	X			X	X	Port E0	SCI Transmit Data Out
62	1	27	PE1/RDI	I/O	C_T		**X**	X			X	X	Port E1	SCI Receive Data In
63	-	-	PE2 (Flash device)	I/O	C_T			**X**					Port E2 **Caution:** In Flash devices this port is always input with weak pull-up.	
			PE2 (ROM device)				**X**				X	X	Port E2 **Caution:** In ROM devices, no weak pull-up present on this port. In LQFP44 this pin is not connected to an internal pull-up like other unbonded pins (See note 4). It is recommended to configure it as output push pull to avoid added current consumption.	
64	-	-	PE3	I/O	C_T		**X**	X			X	X	Port E3	

Notes:

1. In the interrupt input column, “eiX” defines the associated external interrupt vector. If the weak pull-up column (wpu) is merged with the interrupt column (int), then the I/O configuration is pull-up interrupt input, else the configuration is floating interrupt input.

2. In the open drain output column, “T” defines a true open drain I/O (P-Buffer and protection diode to V_{DD} are not implemented). See See “I/O PORTS” on page 46. and Section 12.8 I/O PORT PIN CHARACTER-

INTERRUPTS (Cont'd)

Table 9. Nested Interrupts Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0024h		ei1		ei0		MCC		TLI	
	ISPR0	I1_3	I0_3	I1_2	I0_2	I1_1	I0_1		
	Reset Value	1	1	1	1	1	1	1	1
0025h		SPI				ei3		ei2	
	ISPR1	I1_7	I0_7	I1_6	I0_6	I1_5	I0_5	I1_4	I0_4
	Reset Value	1	1	1	1	1	1	1	1
0026h		AVD		SCI		TIMER B		TIMER A	
	ISPR2	I1_11	I0_11	I1_10	I0_10	I1_9	I0_9	I1_8	I0_8
	Reset Value	1	1	1	1	1	1	1	1
0027h						PWMART		I2C	
	ISPR3					I1_13	I0_13	I1_12	I0_12
	Reset Value	1	1	1	1	1	1	1	1
0028h	**EICR**	IS11	IS10	IPB	IS21	IS20	IPA	TLIS	TLIE
	Reset Value	0	0	0	0	0	0	0	0

ON-CHIP PERIPHERALS (Cont'd)

INPUT CAPTURE CONTROL / STATUS REGISTER (ARTICCSR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
0	0	CS2	CS1	CIE2	CIE1	CF2	CF1

Bit 7:6 = Reserved, always read as 0.

Bit 5:4 = **CS[2:1]** *Capture Sensitivity*
These bits are set and cleared by software. They determine the trigger event polarity on the corresponding input capture channel.
0: Falling edge triggers capture on channel x.
1: Rising edge triggers capture on channel x.

Bit 3:2 = **CIE[2:1]** *Capture Interrupt Enable*
These bits are set and cleared by software. They enable or disable the Input capture channel interrupts independently.
0: Input capture channel x interrupt disabled.
1: Input capture channel x interrupt enabled.

Bit 1:0 = **CF[2:1]** *Capture Flag*
These bits are set by hardware and cleared by software reading the corresponding ARTICRx register. Each CFx bit indicates that an input capture x has occurred.
0: No input capture on channel x.
1: An input capture has occurred on channel x.

INPUT CAPTURE REGISTERS (ARTICRx)

Read only

Reset Value: 0000 0000 (00h)

7							0
IC7	IC6	IC5	IC4	IC3	IC2	IC1	IC0

Bit 7:0 = **IC[7:0]** *Input Capture Data*

These read only bits are set and cleared by hardware. An ARTICRx register contains the 8-bit auto-reload counter value transferred by the input capture channel x event.

16-BIT TIMER (Cont'd)

10.4.3.4 Output Compare

In this section, the index, *i*, may be 1 or 2 because there are two output compare functions in the 16-bit timer.

This function can be used to control an output waveform or indicate when a period of time has elapsed.

When a match is found between the Output Compare register and the free running counter, the output compare function:

- Assigns pins with a programmable value if the OC*i*E bit is set
- Sets a flag in the status register
- Generates an interrupt if enabled

Two 16-bit registers Output Compare Register 1 (OC1R) and Output Compare Register 2 (OC2R) contain the value to be compared to the counter register each timer clock cycle.

	MS Byte	LS Byte
OC*i*R	OC*i*HR	OC*i*LR

These registers are readable and writable and are not affected by the timer hardware. A reset event changes the OC*i*R value to 8000h.

Timing resolution is one count of the free running counter: ($f_{CPU/CC[1:0]}$).

Procedure:

To use the output compare function, select the following in the CR2 register:

- Set the OC*i*E bit if an output is needed then the OCMP*i* pin is dedicated to the output compare *i* signal.
- Select the timer clock (CC[1:0]) (see Table 1).

And select the following in the CR1 register:

- Select the OLVL*i* bit to applied to the OCMP*i* pins after the match occurs.
- Set the OCIE bit to generate an interrupt if it is needed.

When a match is found between OC*i*R register and CR register:

- OCF*i* bit is set.
- The OCMP*i* pin takes OLVL*i* bit value (OCMP*i* pin latch is forced low during reset).
- A timer interrupt is generated if the OCIE bit is set in the CR1 register and the I bit is cleared in the CC register (CC).

The OC*i*R register value required for a specific timing application can be calculated using the following formula:

$$\Delta \text{ OC}i\text{R} = \frac{\Delta t * f_{CPU}}{\text{PRESC}}$$

Where:

Δt = Output compare period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see Table 1)

If the timer clock is an external clock, the formula is:

$$\Delta \text{ OC}i\text{R} = \Delta t * f_{EXT}$$

Where:

Δt = Output compare period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

Clearing the output compare interrupt request (that is, clearing the OCF*i* bit) is done by:

1. Reading the SR register while the OCF*i* bit is set.
2. An access (read or write) to the OC*i*LR register.

The following procedure is recommended to prevent the OCF*i* bit from being set between the time it is read and the write to the OC*i*R register:

- Write to the OC*i*HR register (further compares are inhibited).
- Read the SR register (first step of the clearance of the OCF*i* bit, which may be already set).
- Write to the OC*i*LR register (enables the output compare function and clears the OCF*i* bit).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

10.6.4.9 Clock Deviation Causes

The causes which contribute to the total deviation are:

- D_{TRA}: Deviation due to transmitter error (Local oscillator error of the transmitter or the transmitter is transmitting at a different baud rate).
- D_{QUANT}: Error due to the baud rate quantization of the receiver.
- D_{REC}: Deviation of the local oscillator of the receiver: This deviation can occur during the reception of one complete SCI message assuming that the deviation has been compensated at the beginning of the message.
- D_{TCL}: Deviation due to the transmission line (generally due to the transceivers)

All the deviations of the system should be added and compared to the SCI clock tolerance:

$D_{TRA} + D_{QUANT} + D_{REC} + D_{TCL} < 3.75\%$

10.6.4.10 Noise Error Causes

See also description of Noise error in Section 0.1.4.3 .

Start bit

The noise flag (NF) is set during start bit reception if one of the following conditions occurs:

1. A valid falling edge is not detected. A falling edge is considered to be valid if the 3 consecutive samples before the falling edge occurs are detected as '1' and, after the falling edge occurs, during the sampling of the 16 samples, if one of the samples numbered 3, 5 or 7 is detected as a "1".
2. During sampling of the 16 samples, if one of the samples numbered 8, 9 or 10 is detected as a "1".

Therefore, a valid Start Bit must satisfy both the above conditions to prevent the Noise Flag getting set.

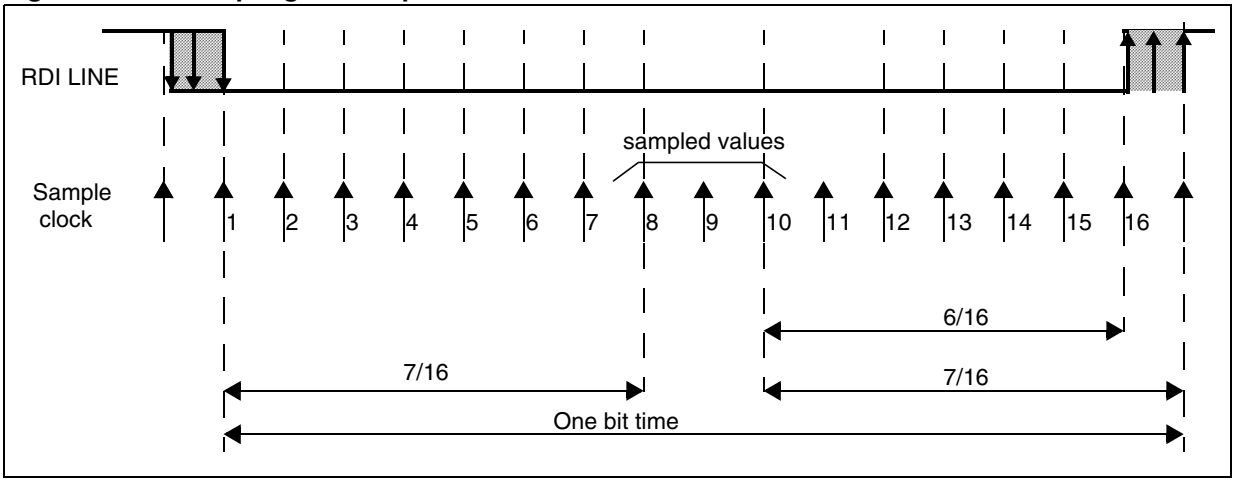
Data Bits

The noise flag (NF) is set during normal data bit reception if the following condition occurs:

- During the sampling of 16 samples, if all three samples numbered 8, 9 and10 are not the same. The majority of the 8th, 9th and 10th samples is considered as the bit value.

Therefore, a valid Data Bit must have samples 8, 9 and 10 at the same value to prevent the Noise Flag getting set.

Figure 63. Bit Sampling in Reception Mode



SERIAL COMMUNICATIONS INTERFACE (Cont'd)

CONTROL REGISTER 2 (SCICR2)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK

Bit 7 = **TIE** *Transmitter interrupt enable*.
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever TDRE=1 in the SCISR register

Bit 6 = TCIE *Transmission complete interrupt enable*
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever TC=1 in the SCISR register

Bit 5 = **RIE** *Receiver interrupt enable*.
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever OR=1 or RDRF=1 in the SCISR register

Bit 4 = **ILIE** *Idle line interrupt enable.*
This bit is set and cleared by software.
0: Interrupt is inhibited
1: An SCI interrupt is generated whenever IDLE=1 in the SCISR register.

Bit 3 = **TE** *Transmitter enable.*
This bit enables the transmitter. It is set and cleared by software.
0: Transmitter is disabled
1: Transmitter is enabled

Notes:

– During transmission, a "0" pulse on the TE bit ("0" followed by "1") sends a preamble (idle line) after the current word.

– When TE is set there is a 1 bit-time delay before the transmission starts.

CAUTION: The TDO pin is free for general purpose I/O only when the TE and RE bits are both cleared (or if TE is never set).

Bit 2 = **RE** *Receiver enable.*
This bit enables the receiver. It is set and cleared by software.
0: Receiver is disabled
1: Receiver is enabled and begins searching for a start bit

Bit 1 = **RWU** *Receiver wake-up.*
This bit determines if the SCI is in mute mode or not. It is set and cleared by software and can be cleared by hardware when a wake-up sequence is recognized.
0: Receiver in Active mode
1: Receiver in Mute mode

Note: Before selecting Mute mode (setting the RWU bit), the SCI must receive some data first, otherwise it cannot function in Mute mode with wake-up by idle line detection.

Bit 0 = **SBK** *Send break.*
This bit set is used to send break characters. It is set and cleared by software.
0: No break character is transmitted
1: Break characters are transmitted

Note: If the SBK bit is set to "1" and then to "0", the transmitter sends a BREAK word at the end of the current word.

I²C BUS INTERFACE (Cont'd)

I²C STATUS REGISTER 1 (SR1)

Read Only

Reset Value: 0000 0000 (00h)

7							0
EVF	ADD10	TRA	BUSY	BTF	ADSL	M/SL	SB

Bit 7 = **EVF** *Event flag.*
This bit is set by hardware as soon as an event occurs. It is cleared by software reading SR2 register in case of error event or as described in Figure 66. It is also cleared by hardware when the interface is disabled (PE=0).
0: No event
1: One of the following events has occurred:

- BTF=1 (Byte received or transmitted)
- ADSL=1 (Address matched in Slave mode while ACK=1)
- SB=1 (Start condition generated in Master mode)
- AF=1 (No acknowledge received after byte transmission)
- STOPF=1 (Stop condition detected in Slave mode)
- ARLO=1 (Arbitration lost in Master mode)
- BERR=1 (Bus error, misplaced Start or Stop condition detected)
- ADD10=1 (Master has sent header byte)
- Address byte successfully transmitted in Master mode.

Bit 6 = **ADD10** *10-bit addressing in Master mode*.
This bit is set by hardware when the master has sent the first byte in 10-bit address mode. It is cleared by software reading SR2 register followed by a write in the DR register of the second address byte. It is also cleared by hardware when the peripheral is disabled (PE=0).

0: No ADD10 event occurred.
1: Master has sent first address byte (header)

Bit 5 = **TRA** *Transmitter/Receiver.*
When BTF is set, TRA=1 if a data byte has been transmitted. It is cleared automatically when BTF is cleared. It is also cleared by hardware after detection of Stop condition (STOPF=1), loss of bus arbitration (ARLO=1) or when the interface is disabled (PE=0).
0: Data byte received (if BTF=1)
1: Data byte transmitted

Bit 4 = **BUSY** *Bus busy*.
This bit is set by hardware on detection of a Start condition and cleared by hardware on detection of a Stop condition. It indicates a communication in progress on the bus. The BUSY flag of the I2CSR1 register is cleared if a Bus Error occurs.
0: No communication on the bus
1: Communication ongoing on the bus
Note:
– The BUSY flag is NOT updated when the interface is disabled (PE=0). This can have consequences when operating in Multimaster mode; i.e. a second active I²C master commencing a transfer with an unset BUSY bit can cause a conflict resulting in lost data. A software workaround consists of checking that the I²C is not busy before enabling the I²C Multimaster cell.

Bit 3 = **BTF** *Byte transfer finished.*
This bit is set by hardware as soon as a byte is correctly received or transmitted with interrupt generation if ITE=1. It is cleared by software reading SR1 register followed by a read or write of DR register. It is also cleared by hardware when the interface is disabled (PE=0).

- Following a byte transmission, this bit is set after reception of the acknowledge clock pulse. In case an address byte is sent, this bit is set only after the EV6 event (See Figure 66). BTF is cleared by reading SR1 register followed by writing the next byte in DR register.
- Following a byte reception, this bit is set after transmission of the acknowledge clock pulse if ACK=1. BTF is cleared by reading SR1 register followed by reading the byte from DR register.

The SCL line is held low while BTF=1.

0: Byte transfer not done
1: Byte transfer succeeded

Bit 2 = **ADSL** *Address matched (Slave mode).*
This bit is set by hardware as soon as the received slave address matched with the OAR register content or a general call is recognized. An interrupt is generated if ITE=1. It is cleared by software reading SR1 register or by hardware when the interface is disabled (PE=0).

The SCL line is held low while ADSL=1.

0: Address mismatched or not received
1: Received address matched

I²C BUS INTERFACE (Cont'd)

Bit 1 = **M/SL** *Master/Slave.*
This bit is set by hardware as soon as the interface is in Master mode (writing START=1). It is cleared by hardware after detecting a Stop condition on the bus or a loss of arbitration (ARLO=1). It is also cleared when the interface is disabled (PE=0).
0: Slave mode
1: Master mode

Bit 0 = **SB** *Start bit (Master mode).*
This bit is set by hardware as soon as the Start condition is generated (following a write START=1). An interrupt is generated if ITE=1. It is cleared by software reading SR1 register followed by writing the address byte in DR register. It is also cleared by hardware when the interface is disabled (PE=0).
0: No Start condition
1: Start condition generated

I²C STATUS REGISTER 2 (SR2)
Read Only
Reset Value: 0000 0000 (00h)

7							0
0	0	0	AF	STOPF	ARLO	BERR	GCAL

Bit 7:5 = Reserved. Forced to 0 by hardware.

Bit 4 = **AF** *Acknowledge failure*.
This bit is set by hardware when no acknowledge is returned. An interrupt is generated if ITE=1. It is cleared by software reading SR2 register or by hardware when the interface is disabled (PE=0).

The SCL line is not held low while AF=1 but by other flags (SB or BTF) that are set at the same time.

0: No acknowledge failure
1: Acknowledge failure
Note:
– When an AF event occurs, the SCL line is not held low; however, the SDA line can remain low if the last bits transmitted are all 0. It is then necessary to release both lines by software.

Bit 3 = **STOPF** *Stop detection (Slave mode).*
This bit is set by hardware when a Stop condition is detected on the bus after an acknowledge (if ACK=1). An interrupt is generated if ITE=1. It is cleared by software reading SR2 register or by hardware when the interface is disabled (PE=0).

The SCL line is not held low while STOPF=1.

0: No Stop condition detected
1: Stop condition detected

Bit 2 = **ARLO** *Arbitration lost*.
This bit is set by hardware when the interface loses the arbitration of the bus to another master. An interrupt is generated if ITE=1. It is cleared by software reading SR2 register or by hardware when the interface is disabled (PE=0).

After an ARLO event the interface switches back automatically to Slave mode (M/SL=0).

The SCL line is not held low while ARLO=1.

0: No arbitration lost detected
1: Arbitration lost detected
Note:
– In a Multimaster environment, when the interface is configured in Master Receive mode it does not perform arbitration during the reception of the Acknowledge Bit. Mishandling of the ARLO bit from the I2CSR2 register may occur when a second master simultaneously requests the same data from the same slave and the I²C master does not acknowledge the data. The ARLO bit is then left at 0 instead of being set.

Bit 1 = **BERR** *Bus error.*
This bit is set by hardware when the interface detects a misplaced Start or Stop condition. An interrupt is generated if ITE=1. It is cleared by software reading SR2 register or by hardware when the interface is disabled (PE=0).

The SCL line is not held low while BERR=1.

0: No misplaced Start or Stop condition
1: Misplaced Start or Stop condition
Note:
– If a Bus Error occurs, a Stop or a repeated Start condition should be generated by the Master to re-synchronize communication, get the transmission acknowledged and the bus released for further communication

Bit 0 = **GCAL** *General Call (Slave mode).*
This bit is set by hardware when a general call address is detected on the bus while ENGC=1. It is cleared by hardware detecting a Stop condition (STOPF=1) or when the interface is disabled (PE=0).

0: No general call address detected on bus
1: general call address detected on bus

11 INSTRUCTION SET

11.1 CPU ADDRESSING MODES

The CPU features 17 different addressing modes which can be classified in seven main groups:

Addressing Mode	Example
Inherent	nop
Immediate	ld A,#$55
Direct	ld A,$55
Indexed	ld A,($55,X)
Indirect	ld A,([$55],X)
Relative	jrne loop
Bit operation	bset byte,#5

The CPU Instruction set is designed to minimize the number of bytes required per instruction: To do so, most of the addressing modes may be subdivided in two submodes called long and short:

– Long addressing mode is more powerful because it can use the full 64 Kbyte address space, however it uses more bytes and more CPU cycles.

– Short addressing mode is less powerful because it can generally only access page zero (0000h - 00FFh range), but the instruction size is more compact, and faster. All memory to memory instructions use short addressing modes only (CLR, CPL, NEG, BSET, BRES, BTJT, BTJF, INC, DEC, RLC, RRC, SLL, SRL, SRA, SWAP)

The ST7 Assembler optimizes the use of long and short addressing modes.

Table 26. CPU Addressing Mode Overview

Mode			Syntax	Destination	Pointer Address (Hex.)	Pointer Size (Hex.)	Length (Bytes)
Inherent			nop				+ 0
Immediate			ld A,#$55				+ 1
Short	Direct		ld A,$10	00..FF			+ 1
Long	Direct		ld A,$1000	0000..FFFF			+ 2
No Offset	Direct	Indexed	ld A,(X)	00..FF			+ 0
Short	Direct	Indexed	ld A,($10,X)	00..1FE			+ 1
Long	Direct	Indexed	ld A,($1000,X)	0000..FFFF			+ 2
Short	Indirect		ld A,[$10]	00..FF	00..FF	byte	+ 2
Long	Indirect		ld A,[$10.w]	0000..FFFF	00..FF	word	+ 2
Short	Indirect	Indexed	ld A,([$10],X)	00..1FE	00..FF	byte	+ 2
Long	Indirect	Indexed	ld A,([$10.w],X)	0000..FFFF	00..FF	word	+ 2
Relative	Direct		jrne loop	PC+/-127			+ 1
Relative	Indirect		jrne [$10]	PC+/-127	00..FF	byte	+ 2
Bit	Direct		bset $10,#7	00..FF			+ 1
Bit	Indirect		bset [$10],#7	00..FF	00..FF	byte	+ 2
Bit	Direct	Relative	btjt $10,#7,skip	00..FF			+ 2
Bit	Indirect	Relative	btjt [$10],#7,skip	00..FF	00..FF	byte	+ 3

12.2 ABSOLUTE MAXIMUM RATINGS

Stresses above those listed as “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.2.1 Voltage Characteristics

Symbol	Ratings	Maximum value	Unit
V_{DD} - V_{SS}	Supply voltage	6.5	V
V_{PP} - V_{SS}	Programming Voltage	13	
V_{IN} 1) & 2)	Input Voltage on true open drain pin	V_{SS}-0.3 to 6.5	
	Input voltage on any other pin	V_{SS}-0.3 to V_{DD}+0.3	
$\lvert\Delta V_{DDx}\rvert$ and $\lvert\Delta V_{SSx}\rvert$	Variations between different digital power pins	50	mV
$\lvert V_{SSA} - V_{SSx}\rvert$	Variations between digital and analog ground pins	50	
$V_{ESD(HBM)}$	Electro-static discharge voltage (Human Body Model)	see section 12.7.3 on page 155	
$V_{ESD(MM)}$	Electro-static discharge voltage (Machine Model)		

12.2.2 Current Characteristics

Symbol	Ratings	Maximum value	Unit
I_{VDD}	Total current into V_{DD} power lines (source) 3)	150	mA
I_{VSS}	Total current out of V_{SS} ground lines (sink) 3)	150	
I_{IO}	Output current sunk by any standard I/O and control pin	25	mA
	Output current sunk by any high sink I/O pin	50	
	Output current source by any I/Os and control pin	- 25	
$I_{INJ(PIN)}$ 2) & 4)	Injected current on V_{PP} pin	± 5	
	Injected current on $\overline{\text{RESET}}$ pin	± 5	
	Injected current on OSC1 and OSC2 pins	± 5	
	Injected current on PB0 (Flash devices only)	+ 5	
	Injected current on any other pin 5) & 6)	± 5	
$\Sigma I_{INJ(PIN)}$ 2)	Total injected current (sum of all I/O and control pins) 5)	± 25	

Notes:

1. Directly connecting the $\overline{\text{RESET}}$ and I/O pins to V_{DD} or V_{SS} could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical: 4.7kΩ for $\overline{\text{RESET}}$, 10kΩ for I/Os). For the same reason, unused I/O pins must not be directly tied to V_{DD} or V_{SS}.
2. $I_{INJ(PIN)}$ must never be exceeded. This is implicitly insured if V_{IN} maximum is respected. If V_{IN} maximum cannot be respected, the injection current must be limited externally to the $I_{INJ(PIN)}$ value. A positive injection is induced by $V_{IN}>V_{DD}$ while a negative injection is induced by $V_{IN}<V_{SS}$. For true open-drain pads, there is no positive injection current, and the corresponding V_{IN} maximum must always be respected
3. All power (V_{DD}) and ground (V_{SS}) lines must always be connected to the external supply.
4. Negative injection disturbs the analog performance of the device. See note in “ADC Accuracy” on page 170. For best reliability, it is recommended to avoid negative injection of more than 1.6mA.
5. When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterisation with $\Sigma I_{INJ(PIN)}$ maximum current injection on four I/O port pins of the device.
6. True open drain I/O port pins do not accept positive injection.

SUPPLY CURRENT CHARACTERISTICS (Cont'd)

12.4.3 On-Chip Peripherals

Measured on LQFP64 generic board T_A = 25°C f_{CPU}=4MHz.

Symbol	Parameter	Conditions		Typ	Unit
$I_{DD(TIM)}$	16-bit Timer supply current [1]		V_{DD}=5.0V	50	µA
$I_{DD(ART)}$	ART PWM supply current[2]		V_{DD}=5.0V	75	µA
$I_{DD(SPI)}$	SPI supply current [3]		V_{DD}=5.0V	400	µA
$I_{DD(SCI)}$	SCI supply current [4]		V_{DD}=5.0V	400	µA
$I_{DD(I2C)}$	I2C supply current [5]		V_{DD}=5.0V	175	µA
$I_{DD(ADC)}$	ADC supply current when converting [6]		V_{DD}=5.0V	400	µA

Notes:

1. Data based on a differential I_{DD} measurement between reset configuration (timer counter running at $f_{CPU}/4$) and timer counter stopped (only TIMD bit set). Data valid for one timer.
2. Data based on a differential I_{DD} measurement between reset configuration (timer stopped) and timer counter enabled (only TCE bit set).
3. Data based on a differential I_{DD} measurement between reset configuration (SPI disabled) and a permanent SPI master communication at maximum speed (data sent equal to 55h).This measurement includes the pad toggling consumption.
4. Data based on a differential I_{DD} measurement between SCI low power state (SCID=1) and a permanent SCI data transmit sequence.
5. Data based on a differential I_{DD} measurement between reset configuration (I2C disabled) and a permanent I2C master communication at 100kHz (data sent equal to 55h). This measurement include the pad toggling consumption (27kOhm external pull-up on clock and data lines).
6. Data based on a differential I_{DD} measurement between reset configuration and continuous A/D conversions.

CLOCK AND TIMING CHARACTERISTICS (Cont'd)

12.5.3 Crystal and Ceramic Resonator Oscillators

The ST7 internal clock can be supplied with four different Crystal/Ceramic resonator oscillators. All the information given in this paragraph is based on characterization results with specified typical external components. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. Refer to the crystal/ceramic resonator manufacturer for more details (frequency, package, accuracy...).

Symbol	Parameter	Conditions		Min	Max	Unit
f_{OSC}	Oscillator Frequency [1]	LP: Low power oscillator MP: Medium power oscillator MS: Medium speed oscillator HS: High speed oscillator		1 >2 >4 >8	2 4 8 16	MHz
R_F	Feedback resistor[2]			20	40	kΩ
C_{L1} C_{L2}	Recommended load capacitance versus equivalent serial resistance of the crystal or ceramic resonator (R_S)	R_S=200Ω R_S=200Ω R_S=200Ω R_S=100Ω	LP oscillator MP oscillator MS oscillator HS oscillator	22 22 18 15	56 46 33 33	pF

Symbol	Parameter	Conditions		Typ	Max	Unit
i_2	OSC2 driving current	V_{DD}=5V V_{IN}=V_{SS}	LP oscillator MP oscillator MS oscillator HS oscillator	80 160 310 610	150 250 460 910	µA

Notes:

1. The oscillator selection can be optimized in terms of supply current using an high quality resonator with small R_S value. Refer to crystal/ceramic resonator manufacturer for more details.

2. Data based on characterisation results, not tested in production.

EMC CHARACTERISTICS (Cont'd)

12.7.2 Electro Magnetic Interference (EMI)

Based on a simple application running on the product (toggling 2 LEDs through the I/O ports), the product is monitored in terms of emission. This emission test is in line with the norm SAE J 1752/ 3 which specifies the board and the loading of each pin.

Symbol	Parameter	Conditions	Monitored Frequency Band	Max vs. [f_{OSC}/f_{CPU}][1]		Unit
				8/4MHz	16/8MHz	
S_{EMI}	Peak level	V_{DD}=5V, T_A=+25°C, LQFP64 10x10 package conforming to SAE J 1752/3	0.1MHz to 30MHz	15	20	dBµV
			30MHz to 130MHz	20	27	
			130MHz to 1GHz	7	12	
			SAE EMI Level	2.5	3	-
S_{EMI}	Peak level	60K ROM Devices: V_{DD}=5V, T_A=+25°C, LQFP64 package conforming to SAE J 1752/3	0.1MHz to 30MHz	15	20	dBµV
			30MHz to 130MHz	20	27	
			130MHz to 1GHz	7	12	
			SAE EMI Level	2.5	3	-
S_{EMI}	Peak level	8/16/32K ROM devices: V_{DD}=5V, T_A=+25°C, LQFP44 10x10 package conforming to SAE J 1752/3	0.1MHz to 30MHz	17	21	dBµV
			30MHz to 130MHz	24	30	
			130MHz to 1GHz	18	23	
			SAE EMI Level	3	3.5	-

Notes:

1. Data based on characterization results, not tested in production.
2. Refer to Application Note AN1709 for data on other package types.

EMC CHARACTERISTICS (Cont'd)

12.7.3 Absolute Maximum Ratings (Electrical Sensitivity)

Based on two different tests (ESD and LU) using specific measurement methods, the product is stressed in order to determine its performance in terms of electrical sensitivity. For more details, refer to the application note AN1181.

12.7.3.1 Electro-Static Discharge (ESD)

Electro-Static Discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts*(n+1) supply pin). Two models can be simulated: Human Body Model and Machine Model. This test conforms to the JESD22-A114A/A115A standard.

Absolute Maximum Ratings

Symbol	Ratings	Conditions	Maximum value [1]	Unit
$V_{ESD(HBM)}$	Electro-static discharge voltage (Human Body Model)	T_A=+25°C	2000	V
$V_{ESD(MM)}$	Electro-static discharge voltage (Machine Model)	T_A=+25°C	200	

Notes:

1. Data based on characterization results, not tested in production.

12.7.3.2 Static Latch-Up

- **LU**: 2 complementary static tests are required on 6 parts to assess the latch-up performance. A supply overvoltage (applied to each power supply pin) and a current injection (applied to each input, output and configurable I/O pin) are performed on each sample. This test conforms to the EIA/JESD 78 IC latch-up standard.

Electrical Sensitivities

Symbol	Parameter	Conditions	Class [1]
LU	Static latch-up class	T_A=+125°C conforming to JESD 78	II level A

COMMUNICATION INTERFACE CHARACTERISTICS (Cont'd)

Figure 93. SPI Slave Timing Diagram with CPHA=1[1)]

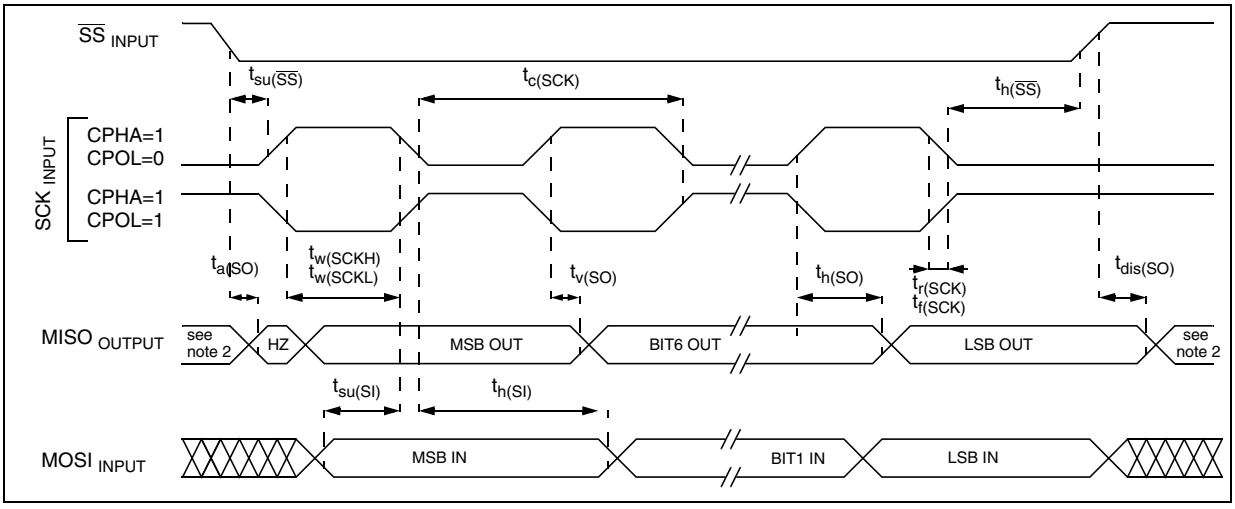
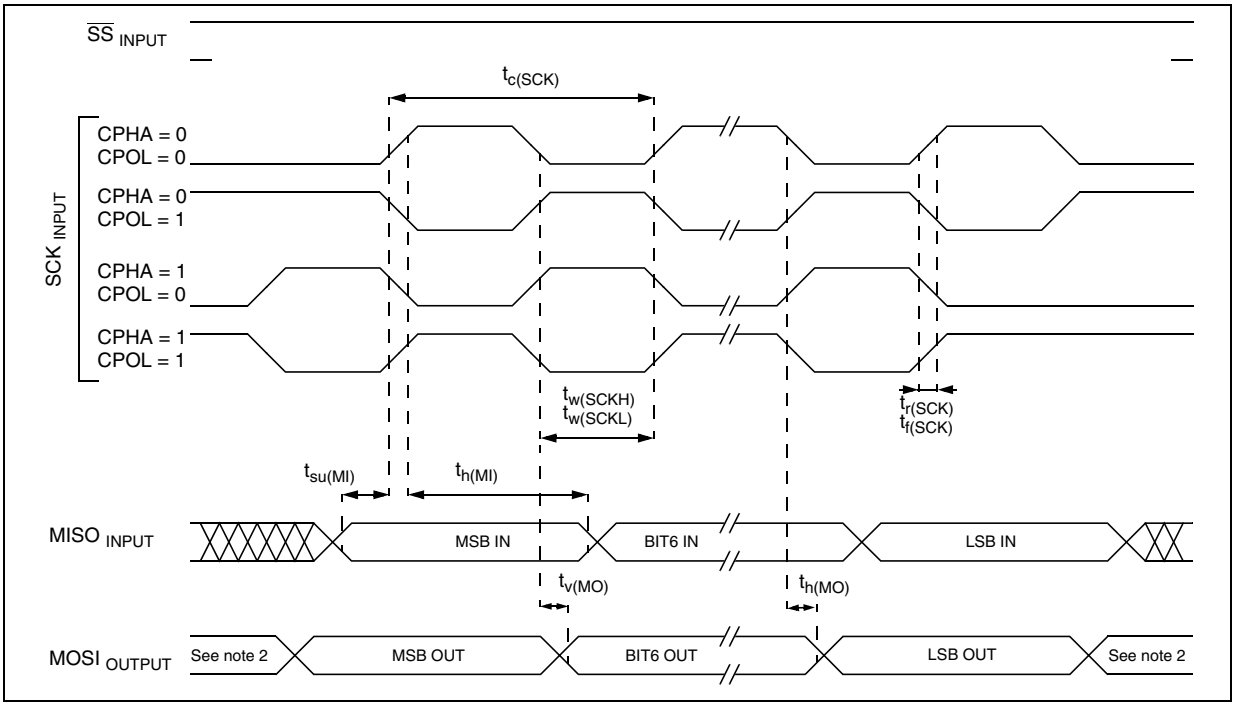


Figure 94. SPI Master Timing Diagram [1)]



Notes:

1. Measurement points are done at CMOS levels: $0.3xV_{DD}$ and $0.7xV_{DD}$.

2. When no communication is on-going the data output line of the SPI (MOSI in master mode, MISO in slave mode) has its alternate function capability released. In this case, the pin status depends of the I/O port configuration.

12.12 10-BIT ADC CHARACTERISTICS

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{ADC}	ADC clock frequency		0.4		2	MHz
V_{AREF}	Analog reference voltage	$0.7*V_{DD} \leq V_{AREF} \leq V_{DD}$	3.8		V_{DD}	V
V_{AIN}	Conversion voltage range [1]		V_{SSA}		V_{AREF}	
R_{AIN}	External input impedance				see Figure 96 and Figure 97	kΩ
C_{AIN}	External capacitor on analog input					pF
f_{AIN}	Variation freq. of analog input signal					Hz
C_{ADC}	Internal sample and hold capacitor			12		pF
t_{ADC}	Conversion time (Sample+Hold) f_{CPU}=8MHz, SPEED=0 f_{ADC}=2MHz			7.5		µs
t_{ADC}	- No of sample capacitor loading cycles - No. of Hold conversion cycles			4 11		$1/f_{ADC}$

Notes:

1. Any added external serial resistor will downgrade the ADC accuracy (especially for resistance greater than 10kΩ). Data based on characterization results, not tested in production.

2. Injecting negative current on any of the analog input pins significantly reduces the accuracy of any conversion being performed on any analog input. Analog pins can be protected against negative injection by adding a Schottky diode (pin to ground). Injecting negative current on digital input pins degrades ADC accuracy especially if performed on a pin close to the analog input pins. Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in Section 12.8 does not affect the ADC accuracy.

14 ST72321 DEVICE CONFIGURATION AND ORDERING INFORMATION

Each device is available for production in user programmable versions (FLASH) as well as in factory coded versions (ROM/FASTROM).

ST72321 devices are ROM versions. ST72P321 devices are Factory Advanced Service Technique ROM (FASTROM) versions: they are factory-programmed HDFlash devices. FLASH devices are shipped to customers with a default content, while ROM/FASTROM factory coded parts contain the code supplied by the customer. This implies that FLASH devices have to be configured by the customer using the Option Bytes while the ROM/FASTROM devices are factory-configured.

14.1 FLASH OPTION BYTES

	STATIC OPTION BYTE 0								STATIC OPTION BYTE							
	7							0	17							0
	WDG		Reserved	VD		Reserved	PKG0	FMP_R	PKG1	RSTC	OSCTYPE		OSCRANGE			PLLOFF
	HALT	SW		1	0						1	0	2	1	0	
Default	1	1	1	0	0	1	1	1	1	1	1	0	1	1	1	1

The option bytes allow the hardware configuration of the microcontroller to be selected. They have no address in the memory map and can be accessed only in programming mode (for example using a standard ST7 programming tool). The default content of the FLASH is fixed to FFh. To program the FLASH devices directly using ICP, FLASH devices are shipped to customers with the internal RC clock source enabled. In masked ROM devices, the option bytes are fixed in hardware by the ROM code (see option list).

OPTION BYTE 0

OPT7= **WDG HALT** *Watchdog and HALT mode*
This option bit determines if a RESET is generated when entering HALT mode while the Watchdog is active.
0: No Reset generation when entering Halt mode
1: Reset generation when entering Halt mode

OPT6= **WDG SW** *Hardware or software watchdog*
This option bit selects the watchdog type.
0: Hardware (watchdog always enabled)
1: Software (watchdog to be enabled by software)

OPT5 = Reserved, must be kept at default value.

OPT4:3= **VD[1:0]** *Voltage detection*
These option bits enable the voltage detection block (LVD, and AVD) with a selected threshold for the LVD and AVD (EVD+AVD).

Selected Low Voltage Detector	VD1	VD0
LVD and AVD Off	1	1
Lowest Threshold: (V_{DD}~3V)	1	0
Med. Threshold (V_{DD}~3.5V)	0	1
Highest Threshold (V_{DD}~4V)	0	0

Caution: If the medium or low thresholds are selected, the detection may occur outside the specified operating voltage range. Below 3.8V, device operation is not guaranteed. For details on the AVD and LVD threshold levels refer to section 12.3.2 on page 141

OPT2 = Reserved, must be kept at default value.

OPT1= **PKG0** *Package selection bit 0*
This option bit isused with the PKG1 bit to select the package.

ST723251 DEVICE CONFIGURATION AND ORDERING INFORMATION (Cont'd)

Figure 106. ROM Factory Coded Device Types